

**AMENDMENTS TO THE CLAIMS**

Please **AMEND** claims 1, 6, and 7 as shown below.

1. (Currently Amended) A thin film transistor (TFT) comprising:  
a channel region having a plurality of primary crystal grain boundaries;  
source and drain regions formed at respective ends of the channel region; and  
offset regions, each comprising inner and outer sides, one of which is formed between  
the channel region and the source region and the other one of which is formed between the  
channel region and the drain region, the inner sides of the offset regions directly contacting the  
channel region, and the outer sides of the offset regions directly contacting the source and drain  
regions,

wherein the thin film transistor is formed so that the primary crystal grain boundaries of a  
polysilicon substrate are not positioned in the offset regions, and

wherein a width of each one of the offset regions is smaller than a distance between the  
primary crystal grain boundaries formed in the channel region.

2. (Canceled)

3. (Original) The thin film transistor according to claim 1, wherein the  
polysilicon substrate is formed by a sequential lateral solidification (SLS) method.

4. (Original) The thin film transistor according to claim 1, wherein the thin film  
transistor is used in an LCD (liquid crystal display) or organic EL (electroluminescent) device.

5. (Previously Presented) The thin film transistor according to claim 1, wherein the primary crystal grain boundaries are substantially perpendicular to a current direction between the source and drain regions of the thin film transistor.

6. (Currently Amended) A thin film transistor (TFT) comprising:  
a channel region;  
source and drain regions respectively formed at opposite sides of the channel region;  
lightly doped drain (LDD) or offset regions, each comprising inner and outer sides,  
formed at respective opposite sides of the channel region and between the source and drain regions, the inner sides of the offset regions directly contacting the channel region, and the outer sides of the offset regions directly contacting the source and drain regions; and  
a plurality of primary crystal grain boundaries, wherein the thin film transistor is formed so that the primary crystal grain boundaries of a polysilicon substrate are positioned in the channel, source and drain regions but not positioned in the LDD or offset regions, and wherein a width of the LDD or offset regions is less than a distance between two adjoining primary crystal grain boundaries.

7. (Currently Amended) A flat panel display device comprising:  
a thin film transistor comprising:  
a channel region;  
offset regions, each comprising inner and outer sides, formed at opposite sides of the channel region, the inner sides of the offset regions directly contacting the channel region;  
source and drain regions respectively formed at outer sides of the offset regions and directly contacting the outer sides of the offset regions; and  
a plurality of primary crystal grain boundaries,

wherein the thin film transistor is formed so that the primary crystal grain boundaries of a polysilicon substrate are not positioned in the offset regions, and wherein a width of the offset regions, is smaller than a distance between the primary crystal grain boundaries.

8. (Canceled)

9. (Original) The flat panel display device according to claim 7, wherein the polysilicon substrate is formed by a sequential lateral solidification (SLS) method.

10. (Original) The flat panel display device according to claim 7, wherein the thin film transistor is used in an LCD (liquid crystal display) or organic EL (electroluminescent) device.

11. (Previously Presented) The flat panel display device according to claim 7, wherein the primary crystal grain boundaries are substantially perpendicular to a current direction between the source and drain regions of the thin film transistor.

12 - 14. (Canceled)